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ISL28113, ISL28213, ISL28413

Single, Dual, Quad General Purpose Micropower, RRIO Operational Amplifier

FN6728
Rev 8.00
April 8, 2015

The ISL28113, ISL28213 and ISL28413 are single, dual and quad channel general purpose micropower, rail-to-rail input and output operational amplifiers with supply voltage range of 1.8V to 5.5V. Key features are a low supply current of 130µA maximum per channel at room temperature, a low bias current and a wide input voltage range, which enables the ISL28x13 devices to be excellent general purpose operational amplifiers for a wide range of applications.

The ISL28113 is available in the SC70-5 and SOT23-5 packages, the ISL28213 is in the MSOP8, SOIC8, SOT23-8 packages and the ISL28413 is in the TSSOP14, SOIC14 packages. All devices operate across the extended temperature range of -40°C to +125°C.

Related Literature

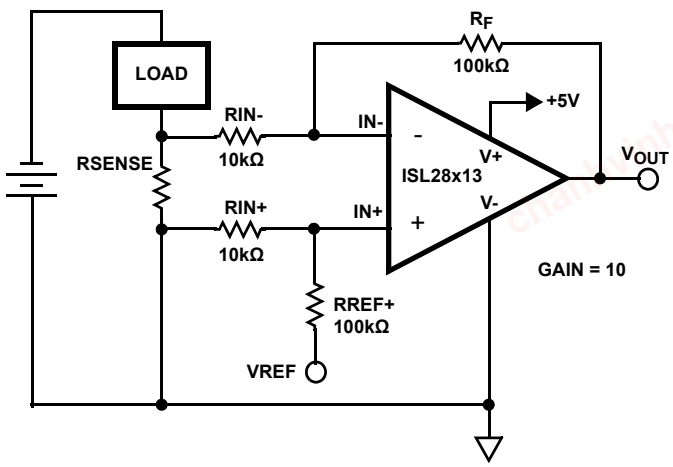
- See AN1519 for "ISL28213/14SOICEVAL2Z Evaluation Board User's Guide"
- See AN1520 for "ISL28113/14SOT23EVAL1Z Evaluation Board User's Guide"
- See AN1542 for "ISL28213/14MSOPEVAL2Z Evaluation Board User's Guide"

Features

- Low current consumption 130µA
- Wide supply range . . . . . 1.8V to 5.5V
- Gain bandwidth product 2MHz
- Input bias current . . . . . 20pA, Max.
- Operating temperature range . . . . . -40°C to +125°C
- Packages
  - ISL28113 (Single) SC70-5, SOT23-5
  - ISL28213 (Dual) MSOP8, SOIC8, SOT23-8
  - ISL28413 (Quad) SOIC14, TSSOP14

Applications

- Power supply control/regulation
- Process control
- Signal gain/buffers
- Active filters
- Current shunt sensing
- Transimpedance amps



SINGLE-SUPPLY, LOW-SIDE CURRENT SENSE AMPLIFIER

FIGURE 1. TYPICAL APPLICATION

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Ordering Information

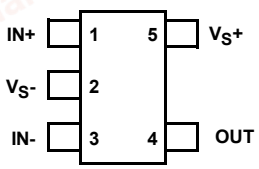
PART NUMBER (Note 4)	PART MARKING	PACKAGE (RoHS Compliant)	PKG. DWG. #
ISL28113FEZ-T7 (Notes 1, 2)	BJA (Note 5)	5 Ld SC-70	P5.049
ISL28113FEZ-T7A (Notes 1, 2)	BJA (Note 5)	5 Ld SC-70	P5.049
ISL28113FHZ-T7 (Notes 1, 2)	BCYA (Note 5)	5 Ld SOT-23	P5.064A
ISL28113FHZ-T7A (Notes 1, 2)	BCYA (Note 5)	5 Ld SOT-23	P5.064A
ISL28213FUZ (Note 2)	8213Z	8 Ld MSOP	M8.118A
ISL28213FUZ-T7 (Notes 1, 2)	8213Z	8 Ld MSOP	M8.118A
ISL28213FBZ (Note 2)	28213 FBZ	8 Ld SOIC	M8.15E
ISL28213FBZ-T7 (Notes 1, 2)	28213 FBZ	8 Ld SOIC	M8.15E
ISL28213FBZ-T13 (Notes 1, 2)	28213 FBZ	8 Ld SOIC	M8.15E
ISL28213FHZ-T7 (Notes 1, 3)	BEKA (Note 5)	8 Ld SOT-23	P8.064
ISL28213FHZ-T7A (Notes 1, 3)	BEKA (Note 5)	8 Ld SOT-23	P8.064
ISL28413FVZ (Note 2)	28413 FVZ	14 Ld TSSOP	MDP0044
ISL28413FVZ-T7 (Notes 1, 2)	28413 FVZ	14 Ld TSSOP	MDP0044
ISL28413FVZ-T13 (Notes 1, 2)	28413 FVZ	14 Ld TSSOP	MDP0044
ISL28413FBZ (Note 2)	28413 FBZ	14 Ld SOIC	MDP0027
ISL28413FBZ-T7 (Notes 1, 2)	28413 FBZ	14 Ld SOIC	MDP0027
ISL28413FBZ-T13 (Notes 1, 2)	28413 FBZ	14 Ld SOIC	MDP0027
ISL28113SOT23EVAL1Z	Evaluation Board		
ISL28213MSOPEVAL2Z	Evaluation Board		
ISL28213SOICEVAL2Z	Evaluation Board		

NOTES:

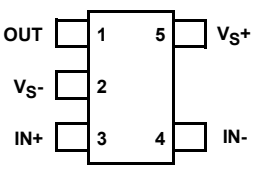
1. Please refer to TB347 for details on reel specifications.
2. These Intersil Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.
3. These Intersil Pb-free plastic packaged products employ special Pb-free material sets; molding compounds/die attach materials and NiPdAu plate - e4 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.
4. For Moisture Sensitivity Level (MSL), please see device information page forr ISL28113, ISL28213, ISL28413. For more information on MSL please see Techbrief TB363.
5. The part marking is located on the bottom of the part.

Pin Configurations

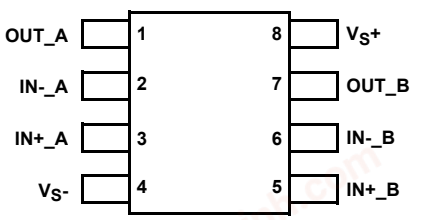
ISL28113
(5 LD SC-70)
TOP VIEW



ISL28113
(5 LD SOT-23)
TOP VIEW



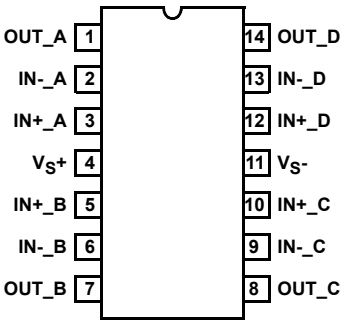
ISL28213
(8 LD MSOP, 8 LD SOIC, 8 LD SOT-23)
TOP VIEW



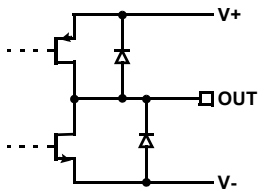
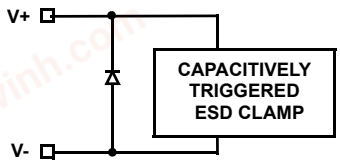
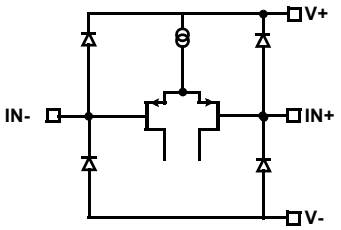
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Pin Configurations (Continued)

ISL28413
(14 LD TSSOP, 14 LD SOIC)
TOP VIEW



Pin Descriptions

PIN NAME	PIN NUMBER				DESCRIPTION	
	5 LD SC-70	5 LD SOT-23	8 LD MSOP, 8 LD SOIC, 8 LD SOT-23	14 LD TSSOP, 14 LD SOIC		
OUT	4	1			Output	 CIRCUIT 1
OUT_A			1	1		
OUT_B			7	7		
OUT_C				8		
OUT_D				14		
V_S-	2	2	4	11	Negative supply voltage	 CIRCUIT 2
IN+	1	3			Positive Input	 CIRCUIT 3
IN+_A			3	3		
IN+_B			5	5		
IN+_C				10		
IN+_D				12		
IN-	3	4			Negative Input	
IN-_A			2	2		
IN-_B			6	6		
IN-_C				9		
IN-_D				13		
V_S+	5	5	8	4	Positive supply voltage	See "CIRCUIT 2"

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Absolute Maximum Ratings (T_A = +25°C)

Supply Voltage 6.5V
Supply Turn-on Voltage Slew Rate 1V/µs
Differential Input Current 20mA
Differential Input Voltage . . . . . V_- - 0.5V to V_+ + 0.5V
Input Voltage . . . . . V_- - 0.5V to V_+ + 0.5V
ESD Rating
  Human Body Model 4000V
  Machine Model
    ISL28113, ISL28213 . . . . . 350V
    ISL28413 . . . . . 400V
  Charged Device Model 2000V

Thermal Information

Thermal Resistance (Typical)	θ_{JA} (°C/W)	θ_{JC} (°C/W)
5 Ld SC-70 (Notes 6, 7)	250	N/A
5 Ld SOT-23 (Notes 6, 7)	225	N/A
8 Ld MSOP (Notes 6, 7)	180	100
8 Ld SOIC Package (Notes 6, 7)	126	90
8 Ld SOT-23 (Notes 6, 7)	240	168
14 Ld TSSOP Package (Notes 6, 7)	120	40
14 Ld SOIC Package (Notes 6, 7)	90	50

Ambient Operating Temperature Range . . . . . -40°C to +125°C
Storage Temperature Range . . . . . -65°C to +150°C
Operating Junction Temperature . . . . . +125°C
Pb-free Reflow Profile . . . . . see TB493

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

NOTES:

6. θ_{JA} is measured with the component mounted on a high effective thermal conductivity test board in free air. See Tech Brief TB379 for details.
7. For θ_{JC}, the "case temp" location is the top of the package.

Electrical Specifications

V_S+ = 5V, V_S- = 0V, R_L = Open, V_{CM} = V_S/2, T_A = +25°C, unless otherwise specified. **Boldface limits apply across the operating temperature range, -40°C to +125°C**, unless otherwise specified.

PARAMETER	DESCRIPTION	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
DC SPECIFICATIONS						
V_{OS}	Input Offset Voltage		-4	0.5	4	mV
			-5		**5**	mV
TCV_{OS}	Input Offset Voltage Temperature Coefficient	-40°C to +125°C		**5**		µV/°C
I_{OS}	Input Offset Current			1	30	pA
I_B	Input Bias Current	ISL28113	-20	3	20	pA
			-100		**100**	pA
		ISL28213, ISL28413	-20	3	20	pA
			-50		**50**	pA
Common Mode Input Voltage Range			**- 0.1V**		**+5.1V**	V
Z_{IN}	Input Impedance			10^{12}		Ω
C_{IN}	Input Capacitance			1		pF
CMRR	Common Mode Rejection Ratio	VCM = -0.1V to 5.1V		72		dB
		-40°C to +125°C		70		dB
PSRR	Power Supply Rejection Ratio	V_S = 1.8V to 5.5V		71		dB
		-40°C to +125°C		70		dB
V_{OH}	Output Voltage Swing, High	R_L = 10kΩ	4.985	4.993		V
			4.98			V
V_{OL}	Output Voltage Swing, Low	R_L = 10kΩ		13	15	mV
					20	mV
V_+	Supply Voltage		1.8		5.5	V
I_S	Supply Current per Amplifier	R_L = OPEN		90	130	µA
					170	µA

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Electrical Specifications $V_S+ = 5V$, $V_S- = 0V$, R_L = Open, $V_{CM} = V_S/2$, $T_A = +25°C$, unless otherwise specified. **Boldface limits apply across the operating temperature range, -40°C to +125°C**, unless otherwise specified. **(Continued)**

PARAMETER	DESCRIPTION	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
I_{SC+}	Output Source Short Circuit Current	R_L = 10Ω to V-		-22		mA
I_{SC-}	Output Sink Short Circuit Current	R_L = 10Ω to V+		16		mA
AC SPECIFICATIONS						
GBWP	Gain Bandwidth Product	V_S = ±2.5V A_V = 100, R_F = 100kΩ, R_G = 1kΩ, R_L = 10kΩ to V_{CM}		2		MHz
e_N V_{P-P}	Peak-to-Peak Input Noise Voltage	V_S = ±2.5V f = 0.1Hz to 10Hz		14		μV_{P-P}
e_N	Input Noise Voltage Density	V_S = ±2.5V f = 1kHz		55		nV/√(Hz)
		V_S = ±2.5V f = 10kHz		29		nV/√(Hz)
i_N	Input Noise Current Density	V_S = ±2.5V f = 1kHz		5		fA/√(Hz)
C_{in}	Differential Input Capacitance	V_S = ±2.5V f = 1MHz		1.0		pF
	Common Mode Input Capacitance			1.3		pF
TRANSIENT RESPONSE						
SR	Slew Rate 20% to 80% V_{OUT}	V_{OUT} = 0.5V to 4.5V		1		V/µs
t_r, t_f, Small Signal	Rise Time, t_r 10% to 90%	V_S = ±2.5V A_V = +1, $V_{OUT} = 0.05V_{P-P}$, R_F = 0Ω, R_L = 10kΩ, C_L = 15pF		100		ns
	Fall Time, t_f 10% to 90%			115		ns
t_s	Settling Time to 0.1%, $4V_{P-P}$ Step	V_S = ±2.5V A_V = +1, R_F = 0Ω, R_L = 10kΩ, C_L = 1.2pF		7.5		µs

NOTE:

8. Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design.

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Typical Performance Curves

V_S = ±2.5V, V_{CM} = 0V, R_L = Open, unless otherwise specified.

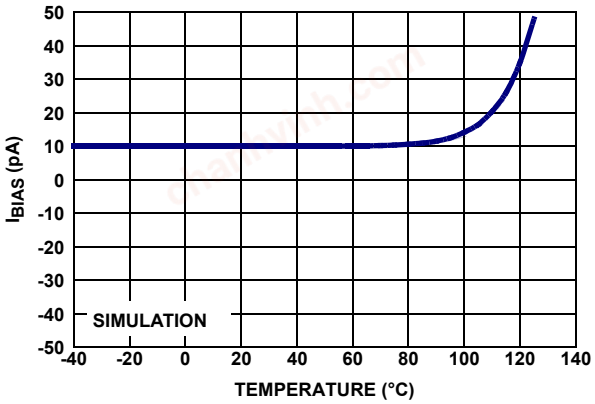


FIGURE 2. INPUT BIAS CURRENT vs TEMPERATURE

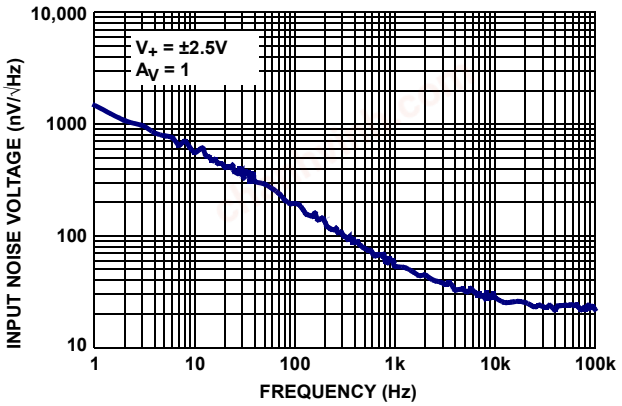


FIGURE 3. INPUT NOISE VOLTAGE SPECTRAL DENSITY

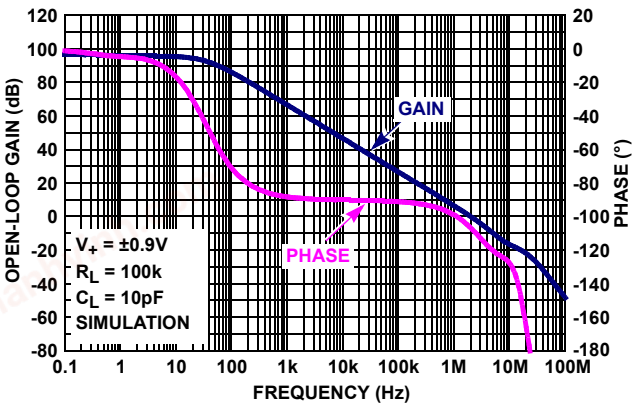


FIGURE 4. OPEN-LOOP GAIN, PHASE vs FREQUENCY, R_L = 100kΩ, C_L = 10pF, V_S = ±0.9V

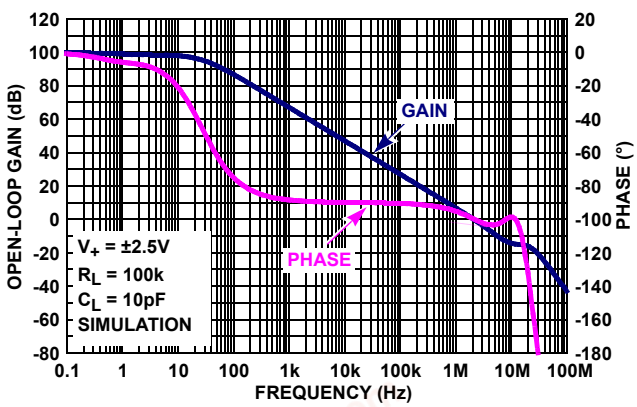


FIGURE 5. OPEN-LOOP GAIN, PHASE vs FREQUENCY, R_L = 100kΩ, C_L = 10pF, V_S = ±2.5V

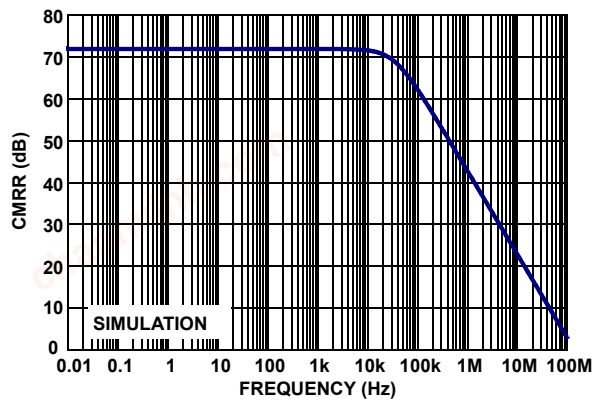


FIGURE 6. CMRR vs FREQUENCY, V_S = ±2.5

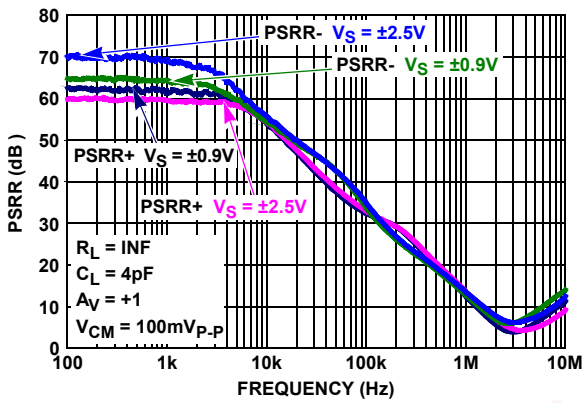


FIGURE 7. PSRR vs FREQUENCY, V_S = ±0.9V, ±2.5V

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Typical Performance Curves $V_S = \pm 2.5V$, $V_{CM} = 0V$, R_L = Open, unless otherwise specified. **(Continued)**

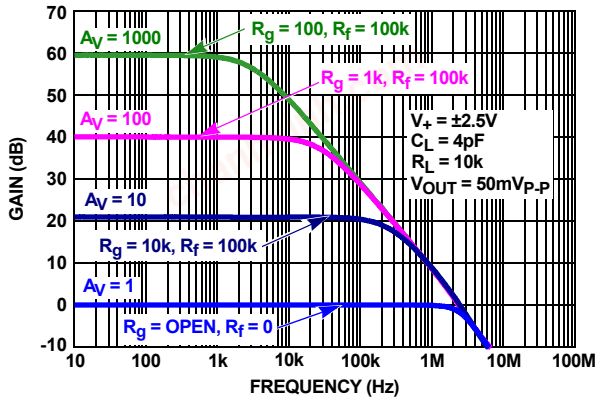


FIGURE 8. FREQUENCY RESPONSE vs CLOSED LOOP GAIN

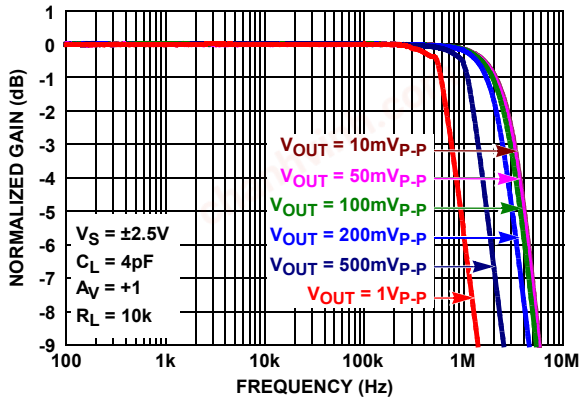


FIGURE 9. FREQUENCY RESPONSE vs V_{OUT}

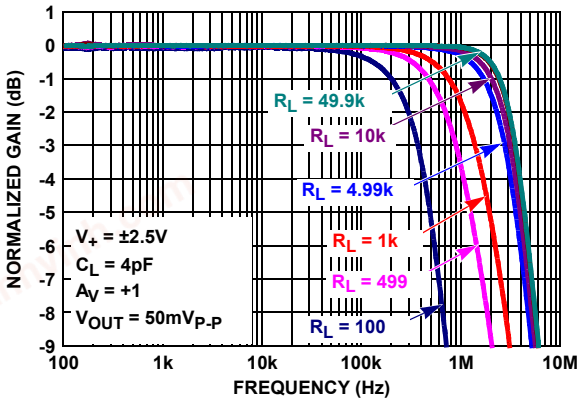


FIGURE 10. GAIN vs FREQUENCY vs R_L

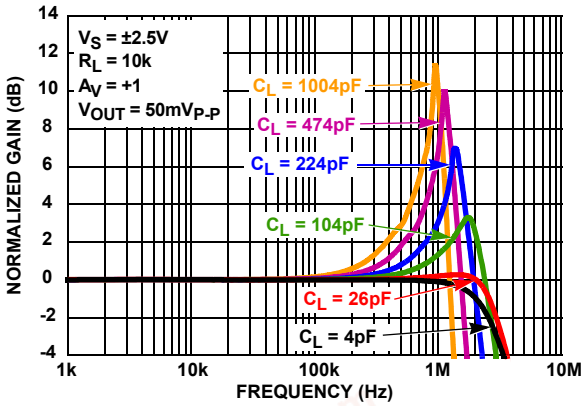


FIGURE 11. GAIN vs FREQUENCY vs C_L

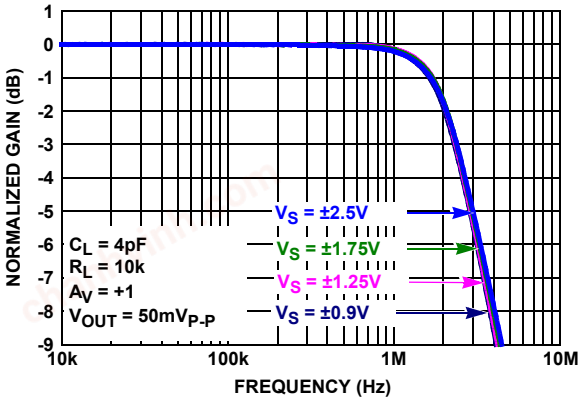


FIGURE 12. GAIN vs FREQUENCY vs SUPPLY VOLTAGE

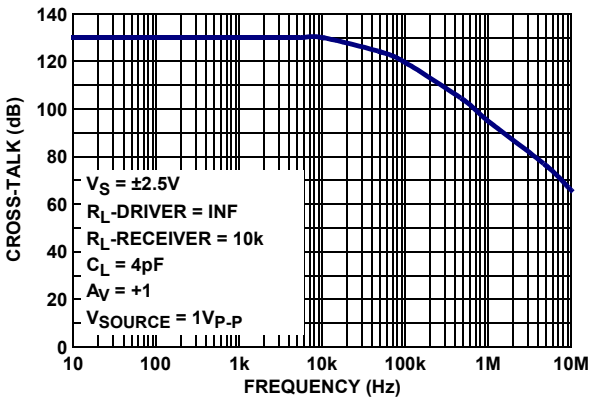


FIGURE 13. CROSSTALK, $V_S = \pm 2.5V$

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Typical Performance Curves $V_S = \pm2.5V$, $V_{CM} = 0V$, R_L = Open, unless otherwise specified. **(Continued)**

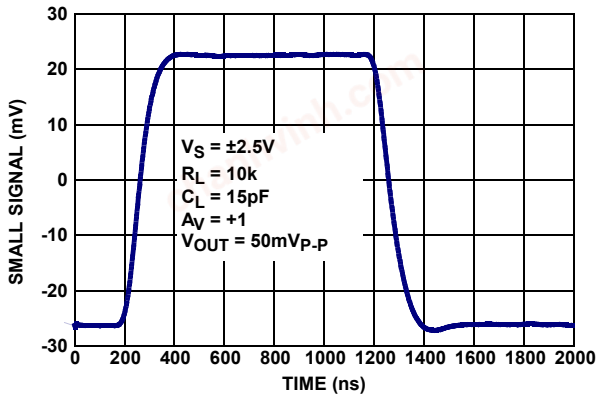


FIGURE 14. SMALL SIGNAL TRANSIENT RESPONSE, $V_S = \pm2.5V$

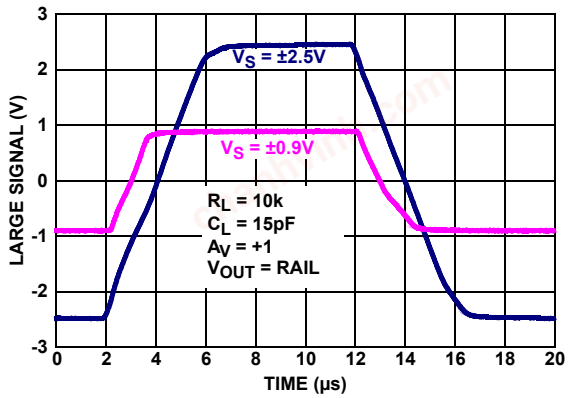


FIGURE 15. LARGE SIGNAL TRANSIENT RESPONSE vs R_L $V_S = \pm0.9V$, $\pm2.5V$

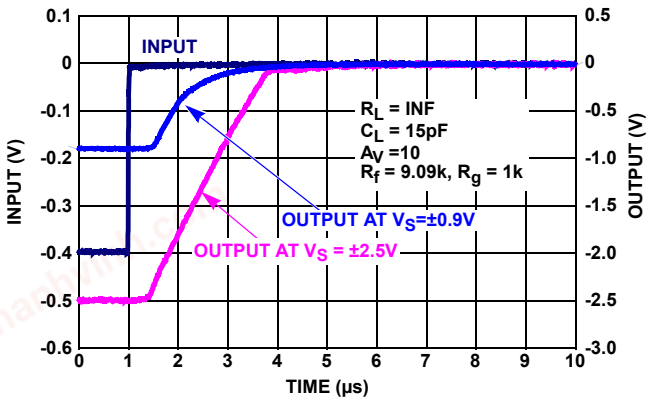


FIGURE 16. NEGATIVE OUTPUT OVERLOAD RESPONSE TIME, $V_S = \pm0.9V, \pm2.5V$

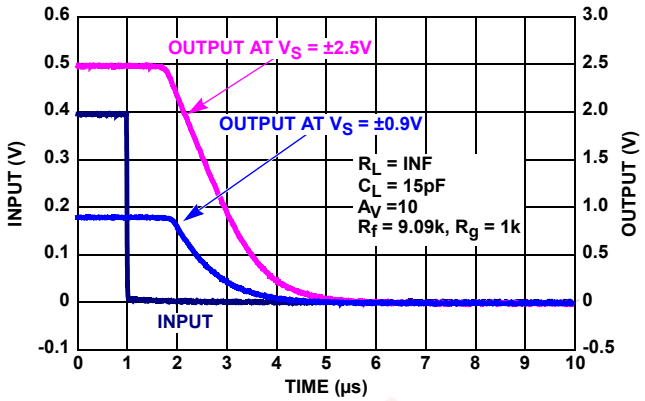


FIGURE 17. POSITIVE OUTPUT OVERLOAD RESPONSE TIME, $V_S = \pm0.9V, \pm2.5V$

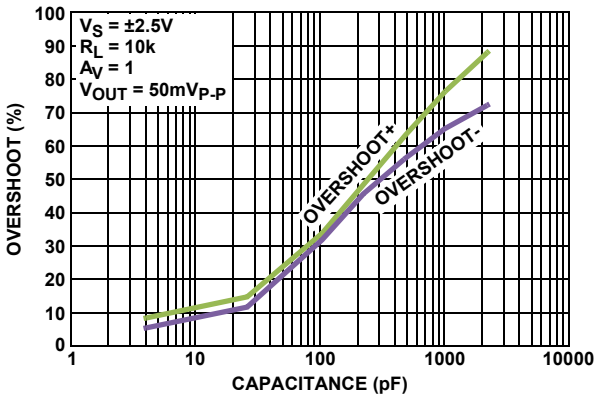


FIGURE 18. % OVERSHOOT vs LOAD CAPACITANCE, $V_S = \pm2.5V$

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Applications Information

Functional Description

The ISL28113, ISL28213 and ISL28413 are single, dual and quad, CMOS rail-to-rail input, output (RRIO) micropower operational amplifiers. They are designed to operate from single supply (1.8V to 5.5V) or dual supply (±0.9V to ±2.75V). The parts have an input common mode range that extends 100mV above and below the power supply voltage rails. The output stage can swing to within 15mV of the supply rails with a 10kΩ load.

Input ESD Diode Protection

All input terminals have internal ESD protection diodes to both positive and negative supply rails, limiting the input voltage to within one diode beyond the supply rails (see “Pin Descriptions - Circuit 1” on page 3). For applications where the input voltage may exceed either power supply voltage by 0.5V or more, an external series resistor must be used to ensure the input currents never exceed 20mA (see Figure 19).

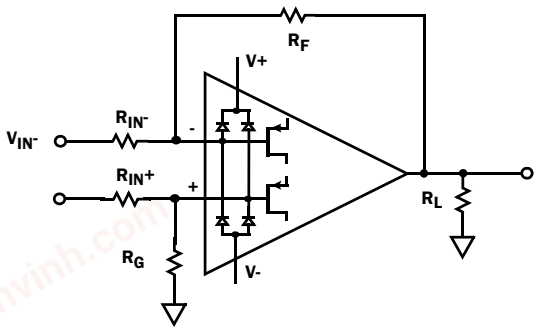


FIGURE 19. INPUT ESD DIODE CURRENT LIMITING

Output Phase Reversal

Output phase reversal is a change of polarity in the amplifier transfer function when the input voltage exceeds the supply voltage. The ISL28113, ISL28213 and ISL28413 are immune to output phase reversal, even when the input voltage is 1V beyond the supplies.

Unused Channels

If the application requires less than all amplifiers one channel, the user must configure the unused channel(s) to prevent it from oscillating. The unused channel(s) will oscillate if the input and output pins are floating. This will result in higher than expected supply currents and possible noise injection into the channel being used. The proper way to prevent this oscillation is to short the output to the inverting input and ground the positive input (as shown in Figure 20).

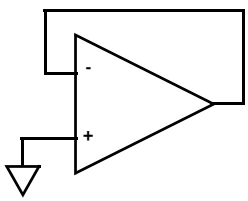


FIGURE 20. PREVENTING OSCILLATIONS IN UNUSED CHANNELS

Power Dissipation

It is possible to exceed the +125°C maximum junction temperatures under certain load, power supply conditions and ambient temperature conditions. It is therefore important to calculate the maximum junction temperature (T_{JMAX}) for all applications to determine if power supply voltages, load conditions, or package type need to be modified to remain in the safe operating area. These parameters are related using Equation 1:

$$T_{JMAX} = T_{MAX} + \theta_{JA} x PD_{MAXTOTAL} \quad \text{(EQ. 1)}$$

Where:

- $P_{DMAXTOTAL}$ is the sum of the maximum power dissipation of each amplifier in the package (PD_{MAX})
- PD_{MAX} for each amplifier can be calculated using Equation 2:

$$PD_{MAX} = V_S \times I_{qMAX} + (V_S - V_{OUTMAX}) \times \frac{V_{OUTMAX}}{R_L} \quad \text{(EQ. 2)}$$

Where:

- T_{MAX} = Maximum ambient temperature
- θ_{JA} = Thermal resistance of the package
- PD_{MAX} = Maximum power dissipation of 1 amplifier
- V_S = Total supply voltage
- I_{qMAX} = Maximum quiescent supply current of 1 amplifier
- V_{OUTMAX} = Maximum output voltage swing of the application
- R_L = Load resistance

ISL28113, ISL28213 and ISL28413 SPICE Model

Figure 21 shows the SPICE model schematic and Figure 22 shows the net list for the SPICE model. The model is a simplified version of the actual device and simulates important AC and DC parameters. AC parameters incorporated into the model are: 1/f and flatband noise, Slew Rate, CMRR, Gain and Phase. The DC parameters are IOS, total supply current and output voltage swing. The model uses typical parameters given in the “Electrical Specifications” Table beginning on page 4. The AVOL is adjusted for 85dB with the dominate pole at 100Hz. The CMRR is set 72dB, f = 35kHz). The input stage models the actual device to present an accurate AC representation. The model is configured for ambient temperature of +25°C.

Figures 23 through 32 show the characterization vs simulation results for the Noise Voltage, Closed Loop Gain vs Frequency, Large Signal 5V Step Response, CMRR and Open-loop Gain Phase.

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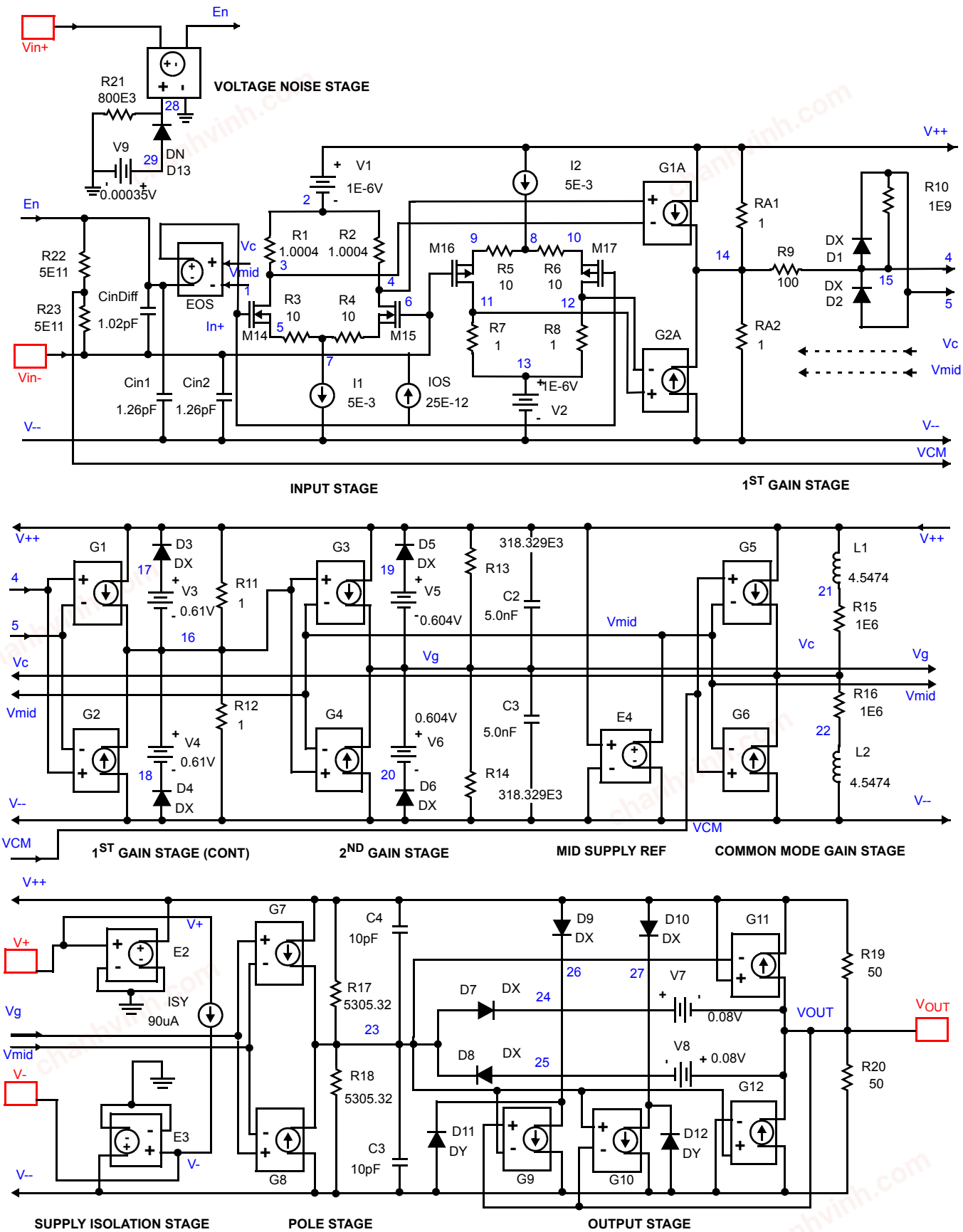


FIGURE 21. SPICE SCHEMATIC

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```
* source ISL28113_SPICEmodel
* Revision D, LaFontaine February 22, 2010 Improved noise performance
* Model for Noise, supply currents, CMRR 72dB f=35kHz, AVOL 85dB f=100Hz
* SR = 1.0V/us, GBWP 2MHz, 2nd pole 3MHz Output voltage clamp and short ckt I limit
*Copyright 2009 by Intersil Corporation
*Refer to data sheet “LICENSE STATEMENT” Use of
*this model indicates your acceptance with the
*terms and provisions in the License Statement.
* Connections:                +input
*                             |       -input
*                             |       |       +Vsupply
*                             |       |       |       -Vsupply
*                             |       |       |       |       output
*                             |       |       |       |       |
.subckt ISL28113subckt      Vin+    Vin-    V+      V-      VOUT
* source ISL28113_DS rev1
*
*Voltage Noise
E_En        VIN+ EN 28 0 1
D_D13         29 28 DN
V_V9        29 0 0.45
R_R21         28 0 30
*
*Input Stage
M_M14         3 1 5 5  NCHANNELMOSFET
M_M15         4 VIN- 6 6 NCHANNELMOSFET
M_M16         11 VIN- 9 9 PMOSISIL
M_M17         12 1 10 10 PMOSISIL
I_I1        7 V-- DC 5e-3
I_I2        V++ 8 DC 5e-3
I_IOS         VIN- 1 DC 25e-12
G_G1A         V++ 14 4 3 1404
G_G2A         V-- 14 11 12 1404
V_V1        V++ 2 1e-6
V_V2        13 V-- 1e-6
R_R1        3 2  1.0004
R_R2        4 2  1.0004
R_R3        5 7  10
R_R4        7 6  10
R_R5        9 8  10
R_R6        8 10  10
R_R7        13 11  1
R_R8        13 12  1
R_RA1         14 V++  1
R_RA2         V-- 14  1
C_CinDif        VIN- EN  1.02E-12
C_Cin1        V-- EN  1.26e-12
C_Cin2        V-- VIN-  1.26e-12
*
*1st Gain Stage
G_G1        V++ 16 15 VMID 334.753e-3
G_G2        V-- 16 15 VMID 334.753e-3
V_V3        17 16 .61
V_V4        16 18 .61
D_D1        15 VMID DX
D_D2        VMID 15 DX
D_D3        17 V++ DX
D_D4        V-- 18 DX
R_R9        15 14  100
R_R10         15 VMID  1e9
R_R11         16 V++  1
R_R12         V-- 16  1
*
*2nd Gain Stage
G_G3        V++ VG 16 VMID 24.893e-3
G_G4        V-- VG 16 VMID 24.893e-3
V_V5        19 VG .604
V_V6        VG 20 .604
D_D5        19 V++ DX
D_D6        V-- 20 DX
R_R13         VG V++  318.329e3
R_R14         V-- VG 318.329e3
C_C2        VG V++ 5E-09
C_C3        V-- VG 5E-09
*
*Mid supply Ref
E_E4        VMID V-- V++ V-- 0.5
E_E2        V++ 0 V+ 0 1
E_E3        V-- 0 V- 0 1
I_ISY       V+ V- DC 90e-6
*
*Common Mode Gain Stage with Zero
G_G5        V++ VC VCM VMID 0.25118
G_G6        V-- VC VCM VMID 0.25118
E_EOS         1 EN VC VMID 1
R_R15         VC 21  0.001
R_R16         22 VC  0.001
R_R22         EN VCM  5e11
R_R23         VCM VIN-  5e11
L_L1        21 V++ 4.547418E-09
L_L2        22 V-- 4.547418E-09
*
*Pole Stage
G_G7        V++ 23 VG VMID 0.18849
G_G8        V-- 23 VG VMID 0.18849
R_R17         23 V++  5.30532
R_R18         V-- 23 5.30532
C_C4        23 V++  1e-8
C_C5        V-- 23  1e-8
*
*Output Stage with Correction Current Sources
G_G9        26 V-- VOUT 23 0.02
G_G10         27 V-- 23 VOUT 0.02
G_G11         VOUT V++ V++ 23 0.02
G_G12         V-- VOUT 23 V-- 0.02
V_V7        24 VOUT .08
V_V8        VOUT 25 .08
D_D7        23 24 DX
D_D8        25 23 DX
D_D9        V++ 26 DX
D_D10         V++ 27 DX
D_D11         V-- 26 DY
D_D12         V-- 27 DY
R_R19         VOUT V++  50
R_R20         V-- VOUT  50
.model pmosisil pmos (kp=16e-3 vto=-0.6)
.model NCHANNELMOSFET nmos (kp=3e-3 vto=0.6)
.model DN D(KF=6.69e-9 AF=1)
.MODEL DX D(IS=1E-12 Rs=0.1)
.MODEL DY D(IS=1E-15 BV=50 Rs=1)
.ends ISL28113subckt
```

FIGURE 22. SPICE NET LIST

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Characterization vs Simulation Results

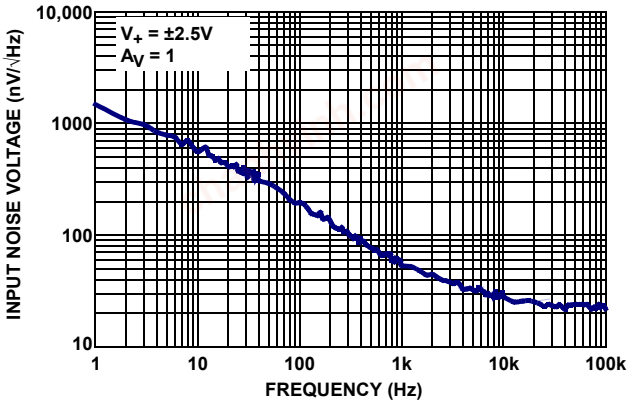


FIGURE 23. CHARACTERIZED INPUT NOISE VOLTAGE

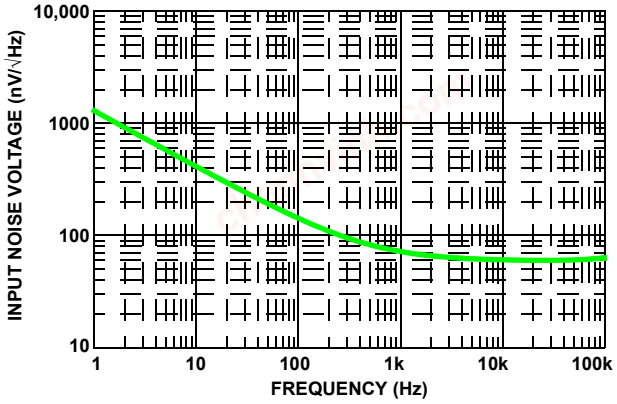


FIGURE 24. SIMULATED INPUT NOISE VOLTAGE

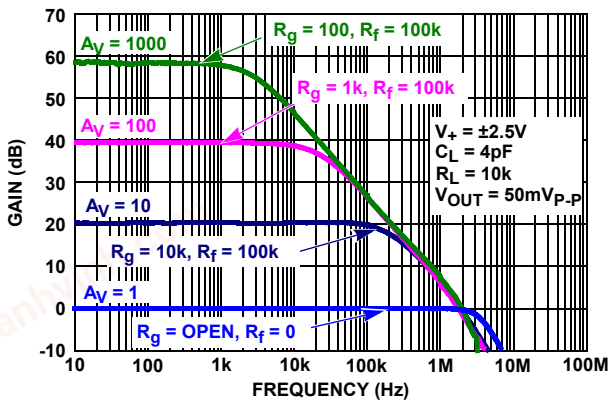


FIGURE 25. CHARACTERIZED CLOSED LOOP GAIN vs FREQUENCY

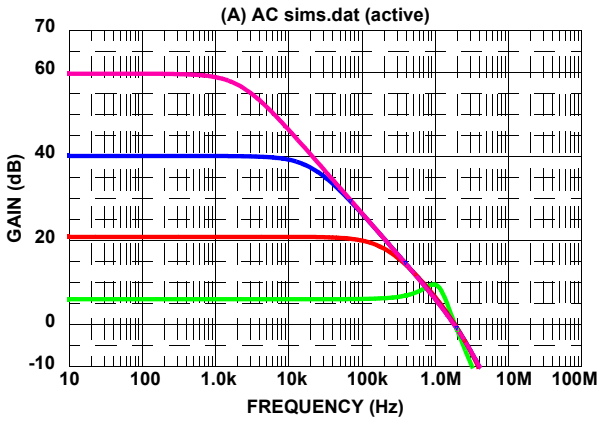


FIGURE 26. SIMULATED CLOSED LOOP GAIN vs FREQUENCY

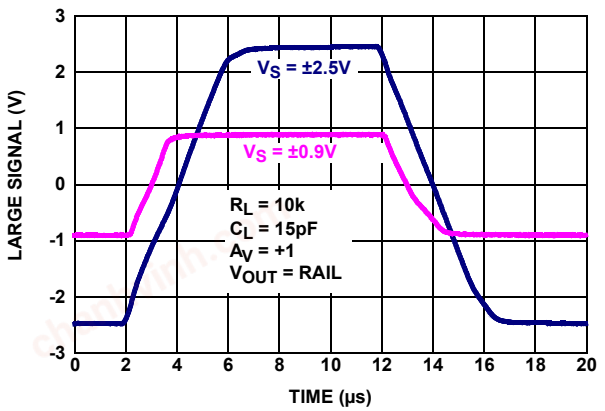


FIGURE 27. CHARACTERIZED LARGE SIGNAL TRANSIENT RESPONSE vs R_L, V_S = ±0.9V, ±2.5V

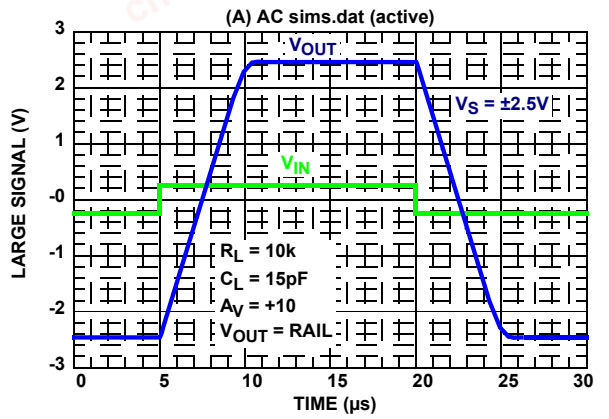


FIGURE 28. SIMULATED LARGE SIGNAL TRANSIENT RESPONSE vs R_L, V_S = ±0.9V, ±2.5V

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Characterization vs Simulation Results (Continued)

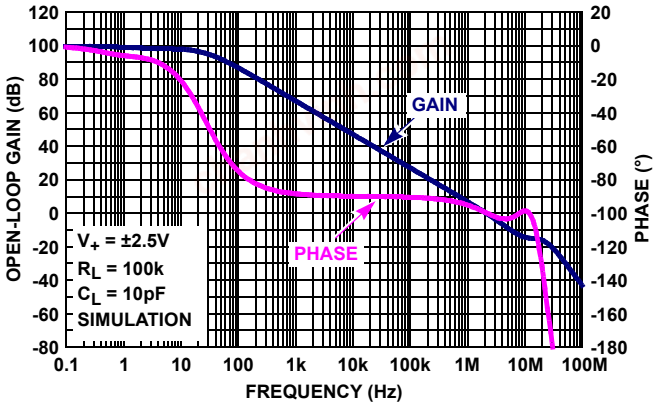


FIGURE 29. SIMULATED (DESIGN) OPEN-LOOP GAIN, PHASE vs FREQUENCY

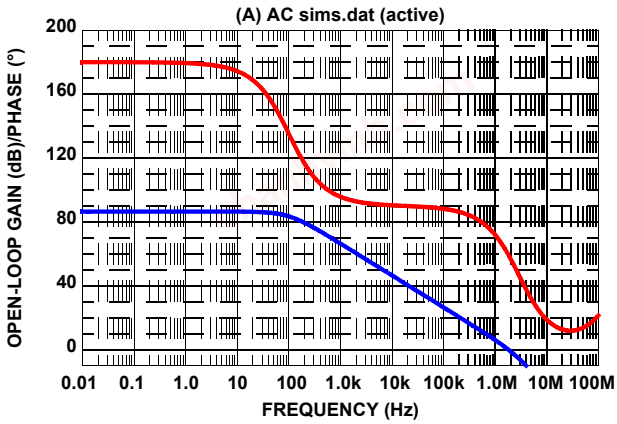


FIGURE 30. SIMULATED (SPICE) OPEN-LOOP GAIN, PHASE vs FREQUENCY

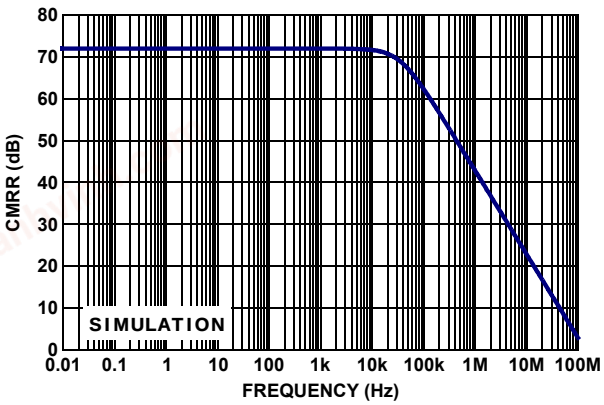


FIGURE 31. SIMULATED (DESIGN) CMRR

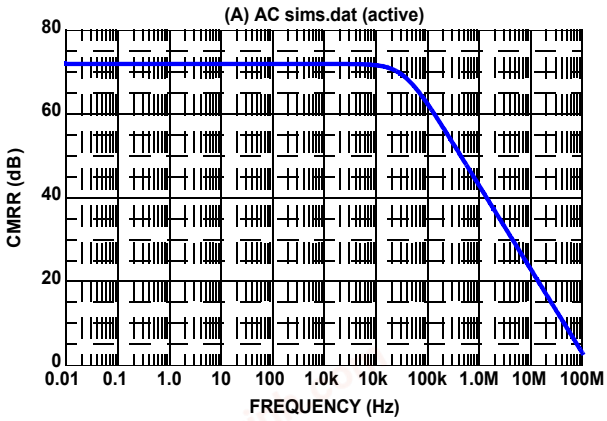


FIGURE 32. SIMULATED (SPICE) CMRR

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Revision History

The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to Web to make sure you have the latest Rev.

DATE	REVISION	CHANGE
4/8/15	FN6728.8	Added a row to the e_N parameter in the Electrical Specification table on page 5 to show low noise. Corrected typo on Figures 15, 16, 17 and 27 by updating the time units from “ms” to “µs”. Updated the About Intersil Verbiage.
10/25/12	FN6728.7	Ordering Information changes on page 2: Removed “italics font” on “ISL28213FHZ-T7A” entry Changed on both the 28213FHZ entries, “Part Marking” from “BCP” to “BEKA” Added Note 3 Lead Finish Note for 8 Ld SOT-23 package Added Note 5 reference for all the SOT-23 and SC-70 entries (6 total), after the part marking, and added the note to Table. Added POD P8.064 on page 23
4/16/12	FN6728.6	Mask changes have been made from RevA to RevB, datasheet updated to reflect new silicon. Page 4: Vos limits changed from ±5mV to ±4mV at room temp and ±6mV to ±5mV at +125°C. TcVos, Max spec removed, typical increased from 2 to 5. Page 7, Replaced Figure 8 with new graph. Page 7, Replaced Figure 11 with new graph. Page 8, Replaced Figure 18 with new graph.
5/18/11	FN6728.5	- On page 2, Ordering Information table: ISL28113FHZ-T7 & -T7A PKG DWG # changed from MDP0038 (Obsoleted) to P5.064A. Removed ISL28213FHZ and added “Coming Soon” to parts ISL28213FHZ-T7A and ISL28413TSSOPEVAL1Z. - On page 3, Pin Descriptions: Circuit 3 diagram, removed anti-parallel diodes from the IN+ to IN- terminals. - On page 4, Absolute Maximum Ratings: changed Differential Input Voltage from "0.5V" to "V_- - 0.5V to V_+ + 0.5V". - On page 4, updated CMRR and PSRR parameters in Electrical Specifications table with test condition specifiying -40°C to +125°C typical parameter. - On page 5, updated Note 6 (“over-temp” note) referenced in MIN and MAX column headings of Electrical Specifications table from "Parameters with MIN and/or MAX limits are 100% tested at +25°C, unless otherwise specified. Temperature limits established by characterization and are not production tested." to new standard "Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design." - On page 9, under “Input ESD Diode Protection,” removed “They also contain back to-back diodes across the input terminals.” Changed “For applications where the input differential voltage is expected to exceed 0.5V, an external series resistor...” to “For applications where the input differential voltage may exceed either power supply voltage by 0.5V or more, an external series resistor...”. Removed “Although the amplifier is fully protected, high input slew rates that exceed the amplifier slew rate (±1V/µs) may cause output distortion.” - On page 9, Figure 19: updated circuit schematic by removing back-to-back input protection diodes. - On page 18, replaced Package Outline Drawing MDP0038 (obsolete) with P5.064A.

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DATE	REVISION	CHANGE
3/23/10	FN6728.4	Page 1, 2nd paragraph - Added "...SOT23-8 packages..." and changed "SO8" to "SOIC8". Also global, changed SO8 to SOIC8 Pg 2, Ordering Information table: Part # ISL28213FEZ changed to ISL28213FHZ and Part Marking changed to "TBD" -Added Related Literature on page 1, updated ordering information by adding Eval boards. -Added to ordering information part number ISL28213FHZ 8 Ld SOT-23 Package as coming soon. -Replaced Figure 24 Simulated Input Noise Voltage with following changes: Y-axis from "10 to 100" to "10,000 to 10" Removed (A) AC sims.dat (active) from top of graph Curve changed to improve noise performance Made changes to Spice Net List as follows: -Changed Revision from "C" to "D" and added improved noise performance to Revision line. -Changed in Voltage Noise "V_V9 29 0 .00035" to "V_V9 29 0 0.45" "R_R21 28 0 800E3 TC=0,0" to "R_R21 28 0 30" -Removed TC=0 in Input Stage from R_R1 through C_Cin2 -Removed TC=0 in 1st Gain Stage from R_R9 through R_R12 -Removed TC=0 in 2nd Gain Stage from R_R13 through C_C3 -Changed in Common Mode Gain Stage with Zero "G_G5 V++ VC VCM VMID 2.5118E-10" to "G_G5 V++ VC VCM VMID 0.25118" "G_G6 V– VC VCM VMID 2.5118E-10" to "G_G6 V– VC VCM VMID 0.25118" Removed TC=0 from R_R16 through R_R23 -Changed in Pole Stage "G_G7 V++ 23 VG VMID 188.49e-6" to 'G_G7 V++ 23 VG VMID 0.18849" "G_G8 V– 23 VG VMID 188.49e-6" to "G_G8 V– 23 VG VMID 0.18849" Removed TC=0 from R_R17 through C_C5 Removed TC=0 in Output Stage with Correction Current Sources from R_R19 and R_R20 Made changes to Spice Schematic Figure 21 as follows: -Input Stage - Modified connection to the EOS (voltage control voltage source) -Added to Thermal Information 8 LD SOT-23 as TBD -Added to pin configuration for the ISL28213 8 Ld SOT-23
12/16/09	FN6728.3	Removed "Coming Soon" from MSOP package options in the "Ordering Information" on page 2. Updated the Theta JA for the MSOP package option from 170°C/W to 180°C/W on page 4.
11/17/09	FN6728.2	Removed "Coming Soon" from SC70 and SOT-23 package options in the "Ordering Information" on page 2.
11/12/09	FN6728.1	Changed theta Ja to 250 from 300. Added license statement (page 10) and reference in spice model (page 12).
10/26/09	FN6728.0	Initial Release

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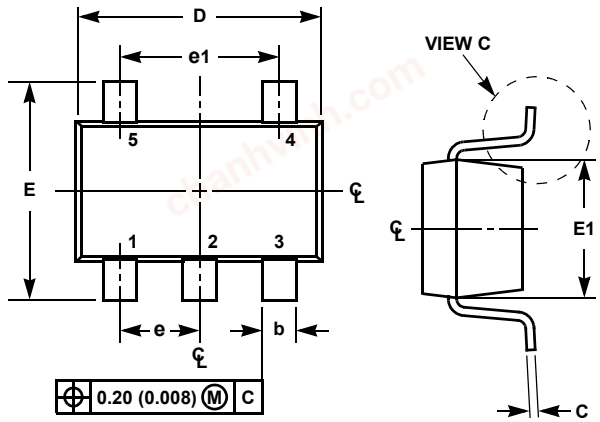
For the most updated datasheet, application notes, related documentation and related parts, please see the respective product information page found at www.intersil.com.

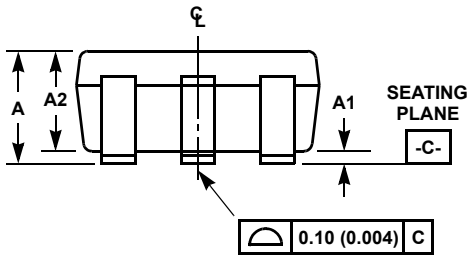
You may report errors or suggestions for improving this datasheet by visiting www.intersil.com/ask.

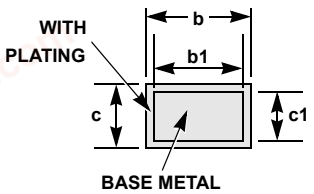
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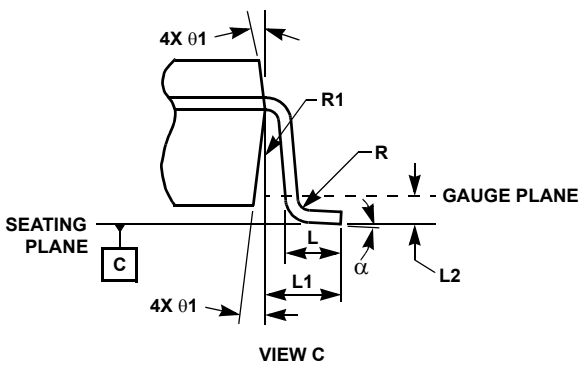
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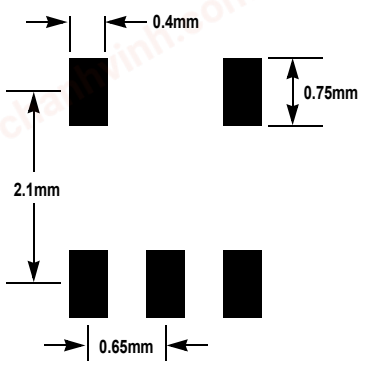
Small Outline Transistor Plastic Packages (SC70-5)











TYPICAL RECOMMENDED LAND PATTERN

P5.049

5 LEAD SMALL OUTLINE TRANSISTOR PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.031	0.043	0.80	1.10	-
A1	0.000	0.004	0.00	0.10	-
A2	0.031	0.039	0.80	1.00	-
b	0.006	0.012	0.15	0.30	-
b1	0.006	0.010	0.15	0.25	
c	0.003	0.009	0.08	0.22	6
c1	0.003	0.009	0.08	0.20	6
D	0.073	0.085	1.85	2.15	3
E	0.071	0.094	1.80	2.40	-
E1	0.045	0.053	1.15	1.35	3
e	0.0256 Ref		0.65 Ref		-
e1	0.0512 Ref		1.30 Ref		-
L	0.010	0.018	0.26	0.46	4
L1	0.017 Ref.		0.420 Ref.		-
L2	0.006 BSC		0.15 BSC		
α	0^o	8^o	0^o	8^o	-
N	5		5		5
R	0.004	-	0.10	-	
R1	0.004	0.010	0.15	0.25	

Rev. 3 7/07

NOTES:

1. Dimensioning and tolerances per ASME Y14.5M-1994.
2. Package conforms to EIAJ SC70 and JEDEC MO-203AA.
3. Dimensions D and E1 are exclusive of mold flash, protrusions, or gate burrs.
4. Footlength L measured at reference to gauge plane.
5. “N” is the number of terminal positions.
6. These Dimensions apply to the flat section of the lead between 0.08mm and 0.15mm from the lead tip.
7. Controlling dimension: MILLIMETER. Converted inch dimensions are for reference only.

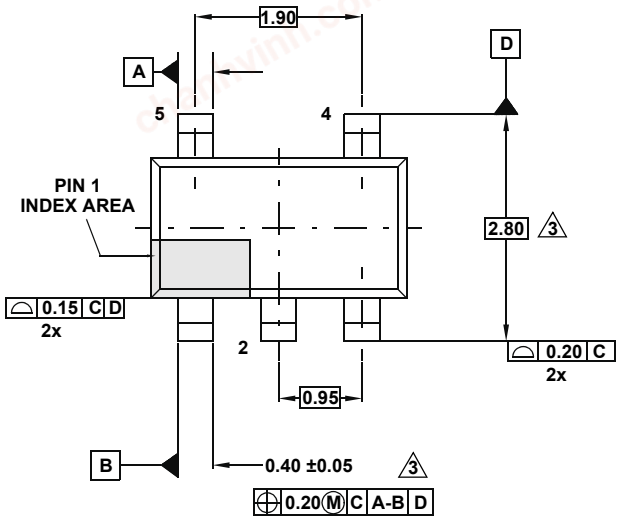
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Package Outline Drawing

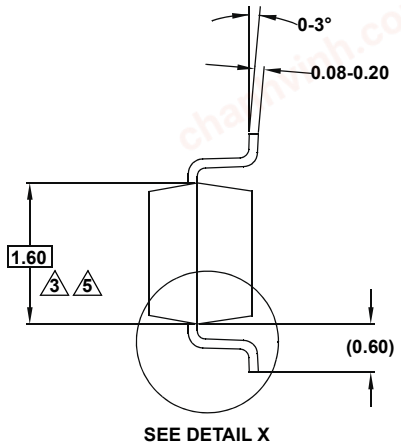
P5.064A

5 LEAD SMALL OUTLINE TRANSISTOR PLASTIC PACKAGE

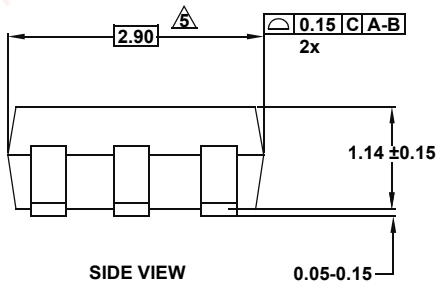
Rev 0, 2/10



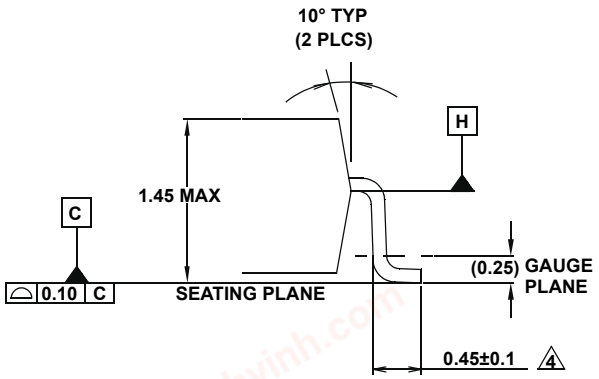
TOP VIEW



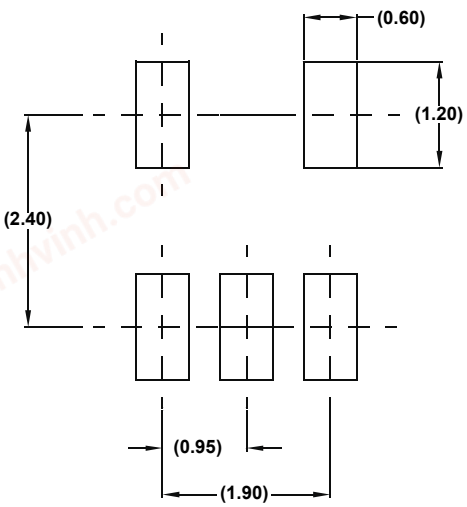
END VIEW



SIDE VIEW



DETAIL "X"



TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. Dimensions are in millimeters.
   Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
3. Dimension is exclusive of mold flash, protrusions or gate burrs.
4. Foot length is measured at reference to guage plane.
5. This dimension is measured at Datum “H”.
6. Package conforms to JEDEC MO-178AA.

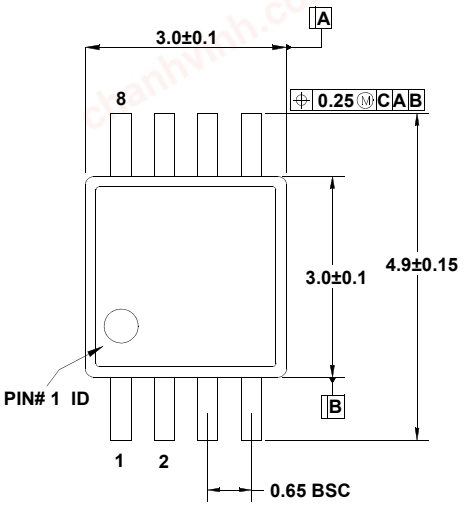
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Package Outline Drawing

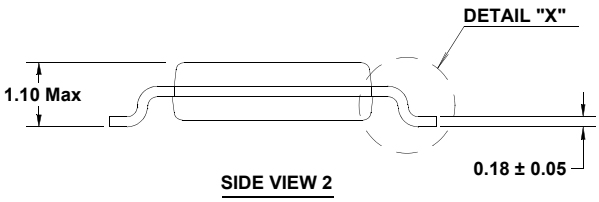
M8.118A

8 LEAD MINI SMALL OUTLINE PLASTIC PACKAGE (MSOP)

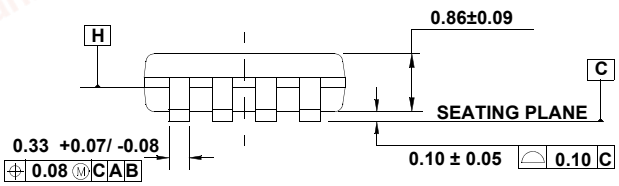
Rev 0, 9/09



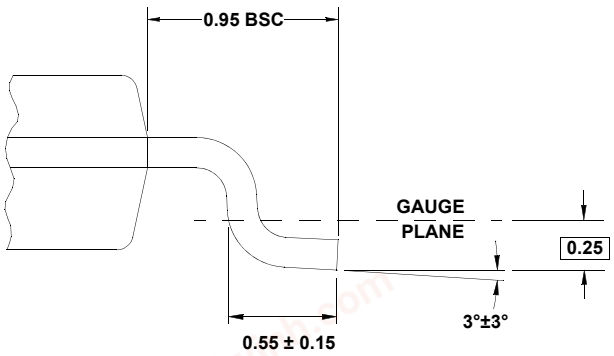
TOP VIEW



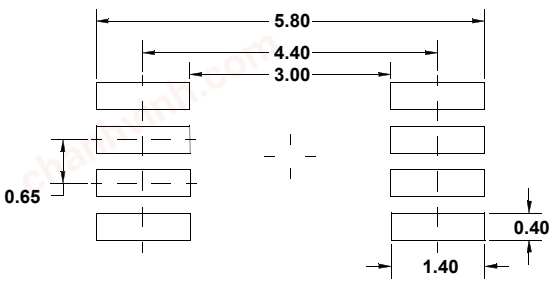
SIDE VIEW 2



SIDE VIEW 1



DETAIL "X"



TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. Dimensions are in millimeters.
2. Dimensioning and tolerancing conform to JEDEC MO-187-AA and AMSE Y14.5m-1994.
3. Plastic or metal protrusions of 0.15mm max per side are not included.
4. Plastic interlead protrusions of 0.25mm max per side are not included.
5. Dimensions “D” and “E1” are measured at Datum Plane “H”.
6. This replaces existing drawing # MDP0043 MSOP 8L.

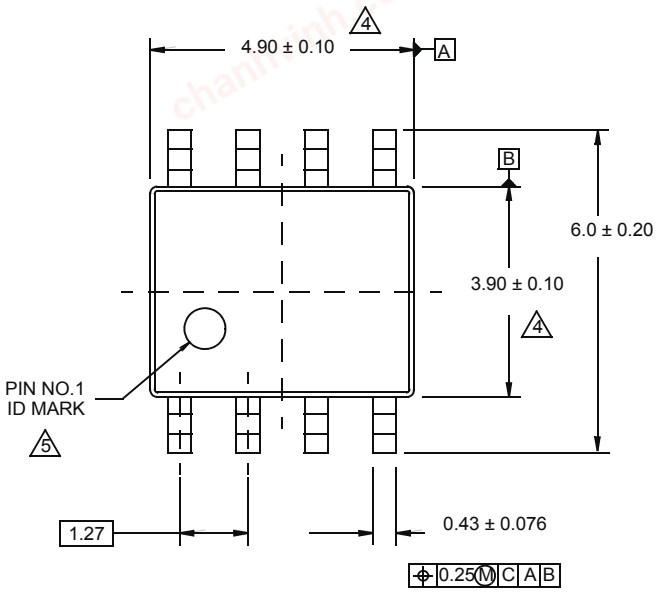
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Package Outline Drawing

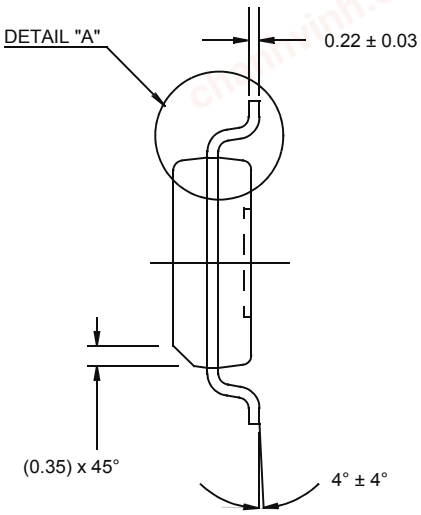
M8.15E

8 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

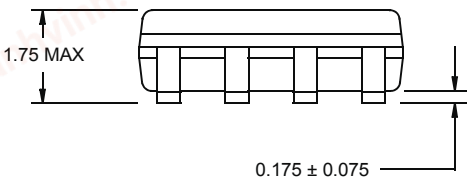
Rev 0, 08/09



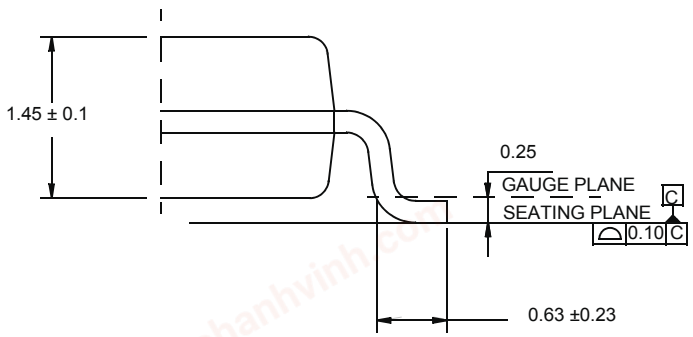
TOP VIEW



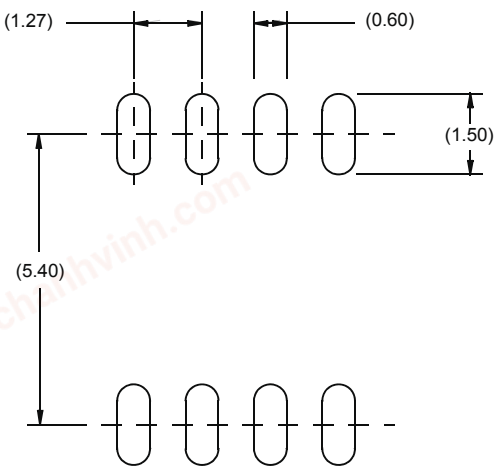
SIDE VIEW "B"



SIDE VIEW "A"



DETAIL "A"



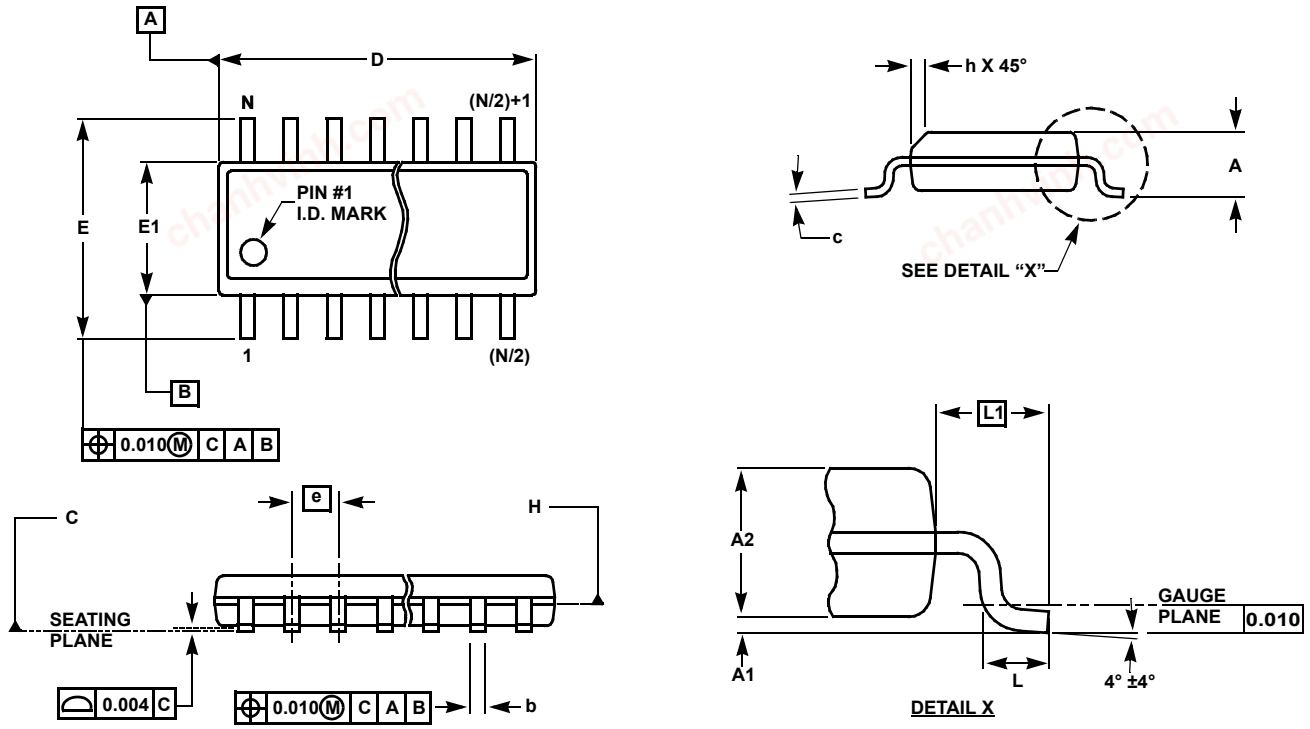
TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. Dimensions are in millimeters.
   Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Dimension does not include interlead flash or protrusions.
   Interlead flash or protrusions shall not exceed 0.25mm per side.
5. The pin #1 identifier may be either a mold or mark feature.
6. Reference to JEDEC MS-012.

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Small Outline Package Family (SO)



MDP0027

SMALL OUTLINE PACKAGE FAMILY (SO)

SYMBOL	INCHES							TOLERANCE	NOTES
	SO-8	SO-14	SO16 (0.150")	SO16 (0.300") (SOL-16)	SO20 (SOL-20)	SO24 (SOL-24)	SO28 (SOL-28)		
A	0.068	0.068	0.068	0.104	0.104	0.104	0.104	MAX	-
A1	0.006	0.006	0.006	0.007	0.007	0.007	0.007	±0.003	-
A2	0.057	0.057	0.057	0.092	0.092	0.092	0.092	±0.002	-
b	0.017	0.017	0.017	0.017	0.017	0.017	0.017	±0.003	-
c	0.009	0.009	0.009	0.011	0.011	0.011	0.011	±0.001	-
D	0.193	0.341	0.390	0.406	0.504	0.606	0.704	±0.004	1, 3
E	0.236	0.236	0.236	0.406	0.406	0.406	0.406	±0.008	-
E1	0.154	0.154	0.154	0.295	0.295	0.295	0.295	±0.004	2, 3
e	0.050	0.050	0.050	0.050	0.050	0.050	0.050	Basic	-
L	0.025	0.025	0.025	0.030	0.030	0.030	0.030	±0.009	-
L1	0.041	0.041	0.041	0.056	0.056	0.056	0.056	Basic	-
h	0.013	0.013	0.013	0.020	0.020	0.020	0.020	Reference	-
N	8	14	16	16	20	24	28	Reference	-

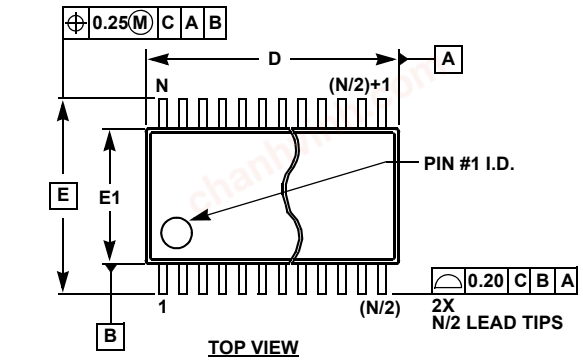
Rev. M 2/07

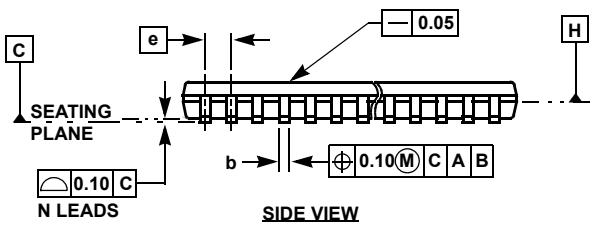
NOTES:

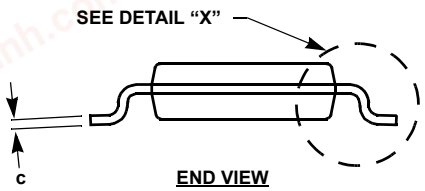
1. Plastic or metal protrusions of 0.006" maximum per side are not included.
2. Plastic interlead protrusions of 0.010" maximum per side are not included.
3. Dimensions "D" and "E1" are measured at Datum Plane "H".
4. Dimensioning and tolerancing per ASME Y14.5M-1994

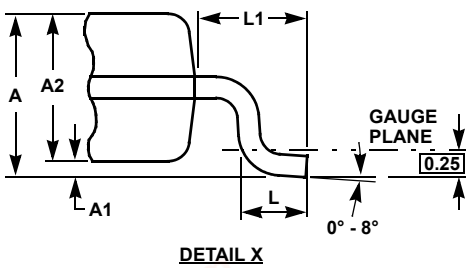
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Thin Shrink Small Outline Package Family (TSSOP)









MDP0044

THIN SHRINK SMALL OUTLINE PACKAGE FAMILY

SYMBOL	MILLIMETERS					TOLERANCE
	14 LD	16 LD	20 LD	24 LD	28 LD	
A	1.20	1.20	1.20	1.20	1.20	Max
A1	0.10	0.10	0.10	0.10	0.10	±0.05
A2	0.90	0.90	0.90	0.90	0.90	±0.05
b	0.25	0.25	0.25	0.25	0.25	+0.05/-0.06
c	0.15	0.15	0.15	0.15	0.15	+0.05/-0.06
D	5.00	5.00	6.50	7.80	9.70	±0.10
E	6.40	6.40	6.40	6.40	6.40	Basic
E1	4.40	4.40	4.40	4.40	4.40	±0.10
e	0.65	0.65	0.65	0.65	0.65	Basic
L	0.60	0.60	0.60	0.60	0.60	±0.15
L1	1.00	1.00	1.00	1.00	1.00	Reference

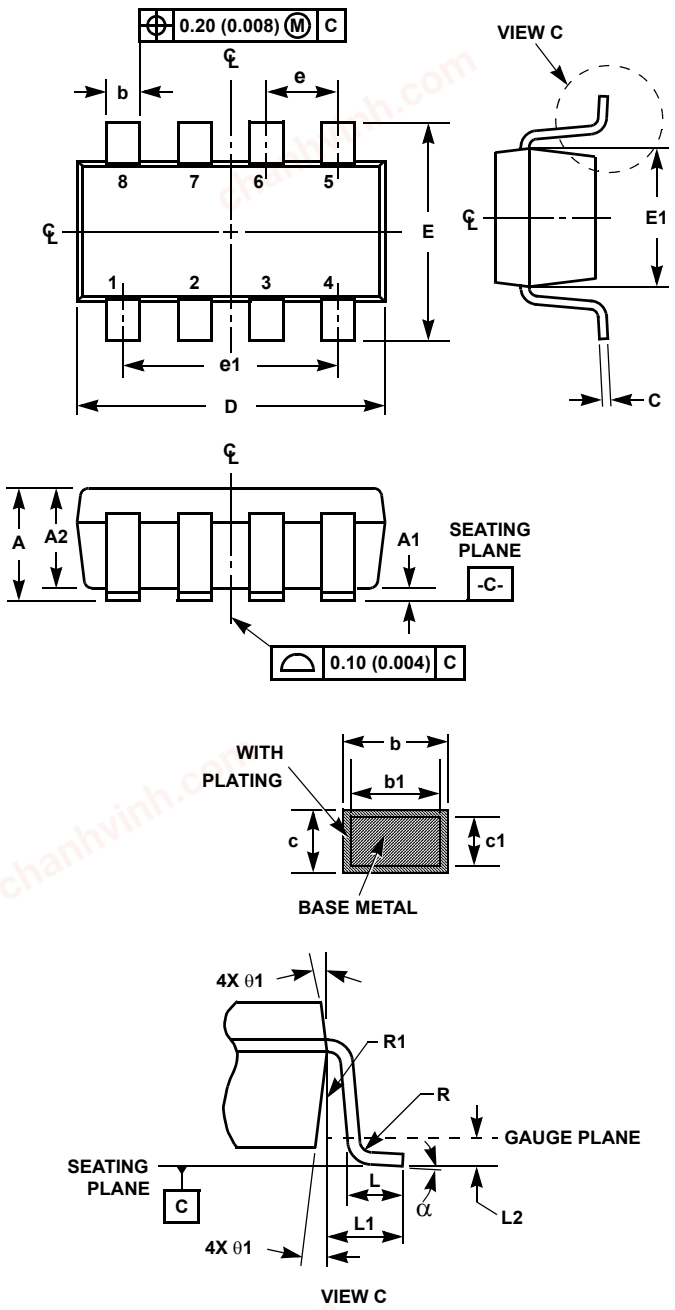
Rev. F 2/07

NOTES:

1. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15mm per side.
2. Dimension "E1" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm per side.
3. Dimensions "D" and "E1" are measured at dAtum Plane H.
4. Dimensioning and tolerancing per ASME Y14.5M-1994.

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Small Outline Transistor Plastic Packages (SOT23-8)



P8.064

8 LEAD SMALL OUTLINE TRANSISTOR PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.036	0.057	0.90	1.45	-
A1	0.000	0.0059	0.00	0.15	-
A2	0.036	0.051	0.90	1.30	-
b	0.009	0.015	0.22	0.38	-
b1	0.009	0.013	0.22	0.33	
c	0.003	0.009	0.08	0.22	6
c1	0.003	0.008	0.08	0.20	6
D	0.111	0.118	2.80	3.00	3
E	0.103	0.118	2.60	3.00	-
E1	0.060	0.067	1.50	1.70	3
e	0.0256 Ref		0.65 Ref		-
e1	0.0768 Ref		1.95 Ref		-
L	0.014	0.022	0.35	0.55	4
L1	0.024 Ref.		0.60 Ref.		
L2	0.010 Ref.		0.25 Ref.		
N	8		8		5
R	0.004	-	0.10	-	
R1	0.004	0.010	0.10	0.25	
α	0^o	8^o	0^o	8^o	-

Rev. 2 9/03

NOTES:

1. Dimensioning and tolerance per ASME Y14.5M-1994.
2. Package conforms to EIAJ SC-74 and JEDEC MO178BA.
3. Dimensions D and E1 are exclusive of mold flash, protrusions, or gate burrs.
4. Footlength L measured at reference to gauge plane.
5. “N” is the number of terminal positions.
6. These Dimensions apply to the flat section of the lead between 0.08mm and 0.15mm from the lead tip.
7. Controlling dimension: MILLIMETER. Converted inch dimensions are for reference only

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